Digiclean

DATA CENTRE EQUIPMENT PRODUCT PORTFOLIO

Custom Solutions for Data Centres and Critical Infrastructure

+27(0)10 312 6424 sales@digiclean.co.za www.digiclean.co.za

Johannesburg: 22 Mac-Mac Road Waterfall Office Park, Midrand, 1685

Cape Town: 2 Enterprise Park, Enterprise Way, Sandown, 7441

SOLUTIONS FOR DIFFERENT BUSINESS SCENARIOS

Cloud Computing — Cloud Platform & Virtualization

Big Data

AI

Edge Computing

Servers

Cloud Computing Node Servers

- 4U4P: NF8480
- 4U2P: NF5466, NF5476, NF5486
- 2U4P: NF8260
- 2U2P: NF5260, NF5280, NF5266
- 1U2P: NF5180
- 1U1P: NF3120
- Rack Scale Server

Mission Critical Servers: TS860, K1 Power E980, K1 Power E950

High Density Servers: i48, i24

AI Computing Acceleration Servers: AGX-2, NF5488, NF5468

Edge Computing Servers: NE5260

Storage

- High-end: HF18000, AS18000, AS6800
- Mass storage: AS13000
- Middle-end: AS5800, AS5600, AS5500
- Entry-level: AS2600, AS2200, AS2150

Switches

FS8500, FS8600, FS8900, FS6700, FS6800

Data Center

MDC2000, CDC2000, SDC2000, RDC2000

Computational Servers


NF5180G7-intel/AMD/ARM


NF5170G7-intel


NF5280G7-intel/AMD/ARM


NF5270G7-intel


NF3280G7-AMD


NF3180G7-AMD

Storage Servers


NF5266G7-intel


NF5466G7-intel


NF5476G7-intel


NF6476V6(JBOD)

Multinode Servers


i22G7-intel/AMD


i24G7-intel/AMD

Key Application Servers


NF8260G7-intel


NF8480G7-intel


TS860G7-intel

Tower Server


NP3020G7-intel

Whole Machine Cabinet Servers


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42U – ORS3000SG7

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KR2280V2

2-Socket Rack Server for All Scenarios

Overview

The KR2280V2 is a mainstream high-end 2U 2-socket rack server that features the 4th Gen Intel® Xeon® Scalable processors, the 4th Gen AMD EPYCTM processors, and the Ampere One processors, spanning three major computing platforms from Intel. In addition, it supports front I/O, liquid cooling, and other deployment options. The server is built upon four key design addition, it supports front I/O, liquid cooling, and other deployment options. The server is built upon four key design principles of break-thru innovation, green and sustainability, intelligence and high efficiency, and open innovation, and offers versatile configurations to cater to the diverse demands of various industries and scenarios.

KR2280V2 | Powered **Intel Processors**

Features

■ Excellent Performance

The server provides the maximum computing, storage, and networking performance supported in the industry and allows flexible combinations through modular design; supports up to 45 × 2.5-inch drives or 20 × 3.5-inch drives and up to 20 PCIe expansion cards (including 2 hot-swap OCP x16 cards and 1 mezz RAID controller card).

■ Flexible System Architecture

Two deployment modes are supported: front I/O and rear I/O, thus effectively improving the operation and maintenance of NICs, optical modules and other thermo -sensitive components in the cold aisle. The server also supports optional air cooling or cold-plated liquid cooling solutions to reduce the PUE of server rooms and comply with carbon neutrality policy.

■ Safety and Reliability

The panel latch and top cover hood latch as well as real-time chassis intrusion alarm prevent unauthorized users from riemoving or installing drives and PCIe devices.
It supports internal USB ports to protect local data security.
It supports the BMC and BIOS dual-chip redundancy mechanism to ensure service continuity.

Specifications

Model	Maintenance	Cooling
KR2280-X2-A0-R0-00	Rear I/O	Air cooling
KR2280-X2-A0-F0-00	Front I/O	Air cooling
KR2280-X2-C0-R0-00	Rear I/O	Cold-plated liquid cooling
Processor	Up to two 4th Gen Intel® Xeon® Scalable processors	
Memory	32 DDR5 DIMM slots, delivering a memory capacity of up to 16 TB	
Storage	Front: Up to 12 × 3.5-inch SAS/SATA/NVMe drives, 24/25 × 2.5-inch SAS/SATA/NVMe drives, or 24 × E3.S SSDs Internal: Up to 4 × 3.5-inch SAS/SATA drives or 10 × 2.5-inch SAS/SATA drives Rear: Up to 4 × 3.5-/2.5-inch SAS/SATA/NVMe drives, 4 × 3.5-inch drives/2 × SATA M.2 SSD/E1.S SSDs, 10 × 2.5-inch SAS/SATA/NVMe drives, or 24 × E3.S SSDs	
I/O Expansion Slot	Internal: 1 × mezz RAID controller card Rear: 8 × PCIe 5.0 slots (6 × full-height 3/4-length + 2 × FHHL), 10 × PCIe 5.0 slots (4 × full-height 3/4-length + 2 × FHHL + 4 × half-height 3/4-length), or 13 × HHHL PCIe 5.0 slots; up to 4 × dual-width GPU Front: 6 × FHHL PCIe slots (for front I/O models)	
Power Supply	1+1 redundant PSUs with the output power of 800W/1,300W/1,600W/2,000W/2,700W	
Operating Temperature	5°C to 50°C (For details, refer to the White Paper)	

KR2280V2 | Powered by AMD Processors

Features

- **Excellent Computing Performance**

Features 4th Gen AMD EPYCTM processors, with up to 96 cores, 12 CCDs, 192 threads, an L3 cache of up to 384 MB, and up to 400W TDP per CPU; supports up to 24 DDR5 DIMMs, delivering superior speed, high availability, and a memory capacity of up to 12 TB.

- **Diverse Storage Configurations**

Up to 20 × 3.5-inch SATA/SAS drives, 28/29 × 2.5-inch SATA/SAS drives, 28 × U.2 NVMe SSDs, or 24 × E3.S SSDs, and internal SATA/NVMe M.2 SSDs, meeting diverse storage needs.

- **Flexible Network Expansion**

Up to 7 or 8 PCIe 5.0 expansion cards or 2 optional OCP 3.0 modules, providing multiple network port options and a more flexible network structure for applications.

Specifications

Model	Maintenance	Cooling
KR2280-E2-A0-F0-00	Rear I/O	Air cooling
KR2280-E2-C0-R0-00	Rear I/O	cold-plated liquid cooling
Processor	Up to two 4th Gen AMD EPYCTM processors	
Memory	24 DDR5 DIMM slots, delivering a memory capacity of up to 12 TB Front: 12 × 3.5-inch SATA/SAS/NVMe drives | 24 × 2.5-inch	
Storage	SATA/SAS/NVMe/E3.S drives | 25 × 2.5-inch SATA/SAS drives (with 4 NVMe drives supported) Internal: 2 × SATA M.2 SSDs or 2 × NVMe M.2 SSDs | 4 × 3.5-inch SATA/SAS drives Rear: Up to 4 × 3.5-inch SAS/SATA drives | Up to 4 × 2.5-inch SAS/SATA/NVMe drives | Up to 2 × M.2 SSDs or 2 × E1.S SSDs	
I/O Expansion Slot	An air-cooled server and a liquid-cooled server support up to 8 and 7 PCIe slots respectively. Both the servers support 2 hot-swap OCP 3.0 x8/x16 cards with the multi-host function.	
Power Supply	1+1 redundant Platinum/Titanium PSUs with the output power of 550W/800W/1,300W/1,600W/2,000W/2,700W	
Operating Temperature	10°C to 35°C (5°C to 45°C for some models. For details, refer to the White Paper)	

KR2280V2 | Powered by ARM Processors

Features

- **Multi-core and Single-thread**

Featuring a remarkably high number of physical cores, it offers stable performance benchmarks for various scenarios and workloads, making it suitable for resource allocation among cloud tenants. This allows for a significant increase in the number of deployable instances.

- **Native System Architecture**

It shares the same system architecture with mobile-side devices and does not require the conversion of instruction sets, thus significantly saving computing power required by cloud gaming and cloud mobile device scenarios.

- **Low TCO**

Thanks to its streamlined instruction set and CPU design, it has a cost advantage and lower power consumption compared to servers powered by x86 CPUs with the same number of threads.

Specifications

Model	Maintenance	Cooling
KR2280-R2-A0-R0-00	Rear I/O	Air cooling
Processor	Up to 2 Ampere One processors	
Memory	32 DDR5 DIMM slots, delivering a memory capacity of up to 16 TB	
Storage	Front: Up to 12 × 3.5-inch SAS/SATA drives, 24/25 × 2.5-inch SAS/SATA/NVMe drives, or 24 × E3.S SSDs Rear: Up to 4 × 2.5-inch SAS/SATA/NVMe drives	
I/O Expansion Slot	Rear: 8 × PCIe 5.0 slots (6 × full-height 3/4-length cards + 2 × FHHL cards) | Up to 4 dual-width GPUs	
Power Supply	1+1 redundant PSUs with the output power of 1,300W/1,600W/2,000W/2,700W	
Operating Temperature	5°C to 50°C (For details, refer to the White Paper)	

KR1280V2

High-density Computing Rack Server

Overview

The KR1280V2 is a mainstream high-end 1U 2-socket rack server that features the 4th Gen Intel® Xeon® Scalable processors, the 4th Gen AMD EPYCTM processors, and the Ampere One processors, spanning three major computing platforms of Intel, AMD, and ARM. It is almost perfectly designed in terms of performance, density, and scalability. In addition, it provides the most diverse storage matrices in the industry, and introduces multi-dimensional cooling solutions (air cooling, cold-plated liquid cooling, and immersion cooling) for 1U models, catering for virtualization, high performance computing, all-flash storage, and other application scenarios and meeting the low PUE requirements of high-density data centers.

KR1280V2 | Powered Intel Processors

Features

■ All-flash Density Optimization

Applicable to the latest storage medium in the industry, the server supports up to 32 hot-swap PCIe 5.0 E1.S SSDs, realizing the maximum parallel storage performance in the industry and offering tens of millions of IOPS to services.

■ Flexible I/O Design

Supports 2 hot-swap OCP 3.0 cards, front I/O, and up to 8 PCIe expansion cards, simplifying operation and maintenance and improving the operating stability of thermo-sensitive components such as NICs and optical modules.

■ High Energy Efficiency and Carbon Reduction

Supports cold-plated liquid cooling and immersion cooling, providing comprehensive liquid cooling solutions for data centers to achieve a PUE below 1.1.

Specifications

Model	Maintenance	Cooling
KR1280-X2-A0-R0-00	Rear I/O	Air cooling Air cooling
KR1280-X2-A0-F0-00	Front I/O	Cold-plated liquid cooling
KR1280-X2-C0-R0-00	Rear I/O	Immersion cooling
KR1280-X2-M0-U0-00	Front I/O	
Processor	Up to two 4th Gen Intel® Xeon® Scalable processors	
Memory	32 DDR5 DIMM slots, delivering a memory capacity of up to 16 TB	
Storage	General	Front I/O
	Front: 32 × E1.S SSDs 12 × 2.5-inch SAS/SATA/NVMe drives (up to 12 × NVMe SSDs) 10 × 2.5-inch SAS/SATA/NVMe drives 8 × 2.5-inch SAS/SATA/NVMe drives + 2 × M.2 SSD + 2 × E1.S SSDs 4 × 3.5-inch SAS/SATA/NVMe drives + 2 × M.2 SSD + 2 × E1.S SSDs 4 × 3.5-inch SAS/SATA/NVMe drives + 4 × 2.5-inch SAS/SATA/NVMe drives Rear: 2 × 2.5-inch SAS/SATA drives Internal: Up to 2 × SATA M.2 SSDs or 2 × NVMe M.2 SSDs	Front: 12 × E1.S SSDs + 2 × M.2 SSDs 4 × E3.S SSDs or 4 × 2.5-inch SAS/SATA/NVMe drives
I/O Expansion Slot	Up to 3 PCIe 5.0 slots, 2 hot-swap OCP 3.0 slots, and 1 internal mezz RAID controller slot	Up to 4 PCIe 5.0 slots (2 front slots and 2 rear slots), 3 hot-swap OCP 3.0 cards (1 front slot and 2 rear slots), and 1 internal mezz RAID controller slot
Power Supply	1+1 redundant CRPS PSUs with the output power of 550W/800W/1,300W/1,600W/2,000W	
Operating Temperature	5°C to 50°C (For details, refer to the White Paper)	

KR1280V2 | Powered by AMD Processors

Features

- **Excellent Computing Performance**

Features 4th Gen AMD EPYCTM processors, with up to 96 cores, 12 CCDs, 192 threads, an L3 cache of up to 384 MB and up to 400W TDP per CPU; supports up to 24 DDR5 DIMMs, delivering superior speed, high availability, and a memory capacity of up to 12TB.

- **Diverse Storage Configurations**

Up to 4 × 3.5-inch SAS/SATA/NVMe drives + 4 × 2.5-inch SAS/SATA/NVMe drives or 12 × 2.5-inch SAS/SATA/NVMe drives, and internal SATA/NVMe M.2 SSDs, meeting diverse storage needs.

- **Flexible Network Expansion**

Up to 2 or 3 PCIe 5.0 expansion cards or 2 optional OCP 3.0 modules, providing multiple network port options and a more flexible network structure for applications.

Specifications

Model	Maintenance	Cooling
KR1280-E2-A0-R0-00	Rear I/O	Air cooling
KR1280-E2-C0-R0-00	Rear I/O	cold-plated liquid cooling
Processor	Up to two 4th Gen AMD EPYCTM processors	
Memory	24 DDR5 DIMM slots, delivering a memory capacity of up to 12 TB	
Storage	Front: 4 × 3.5-inch SAS/SATA/NVMe drives + 4 × 2.5-inch SAS/SATA/NVMe drives | 4 × 3.5-inch SAS/SATA/NVMe drives + 2 × E1.S SSDs + 2 × M.2 SSDs | 12 × 2.5-inch SAS/SATA/NVMe drives Internal: 2 × SATA M.2 SSDs or 2 × PCIe M.2 SSDs (optional)	
I/O Expansion Slot	An air-cooled server and a liquid-cooled server support up to 3 and 2 PCIe 5.0 slots respectively. Both the servers support 2 hot-swap OCP 3.0 x8/x16 cards with the multi-host function.	
Power Supply	1+1 redundant Platinum/Titanium PSUs with the output power of 550W/800W/1,300W/1,600W/2,000W	
Operating Temperature	10°C to 35°C (5°C to 45°C for some models. For details, refer to the White Paper)	

KR1280V2 | Powered by ARM Processors

Features

- **Multi-core and Single-thread**

Featuring a remarkably high number of physical cores, it offers stable performance benchmarks for various scenarios and workloads, making it suitable for resource allocation among cloud tenants. This allows for a significant increase in the number of deployable instances.

- **Native System Architecture for Cloud Gaming and Cloud Mobile Device**

It shares the same system architecture with mobile-side devices and does not require the conversion of instruction sets, thus significantly saving computing power required by cloud gaming and cloud mobile device scenarios.

- **Low TCO**

Thanks to its streamlined instruction set and CPU design, it has a cost advantage and lower power consumption compared to servers powered by x86 CPUs with the same number of threads.

Specifications

Model	Maintenance	Cooling
KR1280-R2-A0-R0-00	Rear I/O	Air cooling
Processor	Up to 2 Ampere One processors	
Memory	32 DDR5 DIMM slots, delivering a memory capacity of up to 16 TB	
Storage	Front: Up to 12 × 2.5-inch SAS/SATA/NVMe drives	
I/O Expansion Slot	Rear: 2 × FHHL PCIe 5.0 slots	
Power Supply	1+1 redundant PSUs with the output power of 1,300W/1,600W/2,000W	
Operating Temperature	5°C to 50°C (For details, refer to the White Paper)	

KR1280V2

Streamlined High-density Computing Rack Server

Overview

The KR1270V2 is a streamlined, cost-effective 1U 2-socket rack server that features the 4th Gen Intel® Xeon® Scalable processors. It combines the minimalist configuration with high computing density to achieve the optimal balance between overall performance and scalability, and meets the light-weight service load needs upon the refined design, catering for cloud computing, virtualization and other high-density computing scenarios whilst satisfying the deployment demand in high-density data centers.

KR1270V2 | Powered Intel Processors

Features

■ Minimalist Design and Flexible Configuration

Flexible and streamlined configuration, with 4 × 3.5-inch drives + 2 × M.2 SSDs + 2 × E1.S SSDs or 10 × 2.5-inch drives and up to 4 PCIe expansion cards, meeting the light-weight service load needs.

■ Security, Reliability, and Service Stability

The redundant design of core components such as BIOS/BMC enables the system to switch to the standby flash for startup in case of a single flash failure. Besides, BMC can be upgraded online without interrupting services, improving the continuity of customer services.

■ Efficient Carbon Reduction and Eco-friendly Energy Saving

The KAYTUS's unique intelligent zoned control technology enables real-time fan speed control and precise air supply for optimal energy efficiency and environmental friendliness. Key components satisfy lead-free requirements (RoHS), with package materials 100% recyclable.

S pecifications

Model	Maintenance	Cooling
KR1270-X2-A0-R0-00	Rear I/O	Air cooling
Processor	Up to two 4th Gen Intel® Xeon® Scalable processors	
Memory	16 DDR5 DIMM slots, delivering a memory capacity of up to 8 TB	
Storage	Front: 10 × 2.5-inch SAS/SATA/NVMe drives | 4 × 3.5-inch SAS/SATA/NVMe drives + 2 × M.2 SSDs + 2 × E1.S SSDs Internal: Up to 2 × M.2 SSDs	
I/O Expansion Slot	Up to 3 PCIe 4.0 cards and 1 internal mezz RAID controller card	
Power Supply	1+1 redundant CRPS PSUs with the output power of 550W/800W/1,300W	
Operating Temperature	5°C to 45°C (For details, refer to the White Paper)	

KR2180V2

2U Dense and Cost-effective Rack Server

Overview

The KR2180V2 is an dense and cost-effective 2U single-socket rack server series that features 4th Gen AMD EPYCTM processor. Designed with multiple cores, high base frequency and large cache, it provides maximized storage and expansion capabilities in a 2U space, making it suitable for application scenarios such as big data, distributed storage, video transcoding and HPC and effectively improving TCO benefits.

KR2180V2 | Powered **AMD Processors** AMD EPYC

Features

■ Powerful Performance

Features one 4th Gen AMD EPYCTM processor, with up to 96 cores, 192 threads, a base frequency of up to 4.4 GHz, and an L3 cache of up to 384 MB; supports 12 memory channels, 24 DDR5 DIMM slots and up to 128 PCIe 5.0 channels per CPU.

■ Ultra-high Scalability

Large local storage: Up to 20 x 3.5-inch SATA/SAS drives, 28/29 x 2.5-inch SATA/SAS drives, 28 x U.2 NVMe SSDs, or 24 × E3.S SSDs.
Ultra-high I/O expansion: Up to 8 full-height PCIe slots and 2 OCP 3.0 slots.

■ Openness and Security

Supports Open BMC standard interfaces, the latest version of Redfish, and DCSCM standardized management modules for cross-plat- form compatibility.
Supports BIOS/BMC chip-level redundancy to enhance firmware security; supports secure erasure of drive data and firmware tamper-proofing.

Specifications

Model	Maintenance	Cooling
KR2180-E2-A0-R0-00	Rear I/O	Air cooling
Processor	One 4th Gen AMD EPYCTM processor	
Memory	24 DDR5 DIMM slots, delivering a memory capacity of up to 12 TB	
Storage	Front: 12 × 3.5-inch SAS/SATA/NVMe drives | 24 × 2.5-inch SAS/SATA/NVMe/E3.S drives | 25 × 2.5-inch SATA/SAS drives (with 4 NVMe drives supported) Internal: 2 × SATA/PCIe M.2 SSDs | 4 × 3.5-inch SATA drives Rear: 4 × 3.5-inch SAS/SATA drives | 4 × 2.5-inch SAS/SATA/NVMe drives	
I/O Expansion Slot	Up to 8 PCIe slots | Up to 2 hot-swap OCP 3.0 x8/x16 slots	
Power Supply	1+1 redundant PSUs	
Operating Temperature	5°C to 45°C (For details, refer to the White Paper)	

KR1180V2

1U Dense and Cost-effective Rack Server

Overview

The KR1180V2 is an dense and cost-effective 1U single-socket rack server series that features 4th Gen AMD EPYC™ processor. It is designed with multiple cores, high base frequency and large cache, providing ultimate computing performance in a 1U high-density space. With balanced networking and expansion features, it saves server room space and is suitable for application scenarios such as cloud computing, virtualization, big data, and distributed all-flash storage.

KR1180V2
Features

Powered
AMD Processors

■ Powerful Performance

Features one 4th Gen AMD EPYC™ processor, with up to 96 cores, 192 threads, a base frequency of up to 4.4 GHz, and an L3 cache of up to 384 MB; supports 12 memory channels, 24 DDR5 DIMM slots and up to 128 PCIe 5.0 channels per CPU.

■ Extremely High Density

Flexible storage: 4 × 3.5-inch drives + 4 × 2.5-inch drive/10 × 2.5-inch drives/16 × E1.S SSDs/8 × 2.5-inch drives + 2 × PCIe slots.
Ultimate I/O: Up to 5 PCIe slots and 2 OCP 3.0 slots.

■ Openness and Security

Supports Open BMC standard interfaces, the latest version of Redfish, and DC-SCM standardized management modules for cross-platform compatibility.
Supports BIOS/BMC chip-level redundancy to enhance firmware security; supports secure erasure of drive data and firmware tamper-proofing.

Specifications

Model	Maintenance	Cooling
KR1180-E2-A0-R0-00	Rear I/O	Air cooling
Processor	One 4th Gen AMD EPYCTM processor	
M emory	24 DDR5 DIMM slots, delivering a memory capacity of up to 12 TB	
Storage	Front: Up to 4 × 3.5-inch SAS/SATA/NVMe drives + 4 × 2.5-inch SAS/SATA/NVMe drives | Up to 10 × 2.5-inch SAS/SATA/NVMe drives | Up to 16 × E1.S SSDs Internal: 2 × SATA/PCIe M.2 SSDs Front: Up to 2 PCIe slots	
I/O Expansion Slot	Rear: Up to 3 PCIe slots | Up to 2 OCP 3.0 x8/x16 slots	
Power Supply	1+1 redundant PSUs	
Operating Temperature	5°C to 45°C (For details, refer to the White Paper)	

KT3020V2

Entry-level Single-socket Tower Server

Overview

The KT3020V2 is an entry-level single-socket tower server series that features Intel® Xeon® E Tatlow series or Pentium® series processor. The KT3020V2 series is designed to provide a reliable and cost-effective hardware basis for customers' overall office, mail, and printing solutions. It can be flexibly expanded based on the customer's specific application environment, and can function as an efficient workstation in complex operating environments.

KT3020V2 | Powered **Intel Processors**

Features

- **High Performance and Low Price**

The server supports one Intel®Xeon E-series Tatlow Platform or Pentium® series processor and 4 DDR4 DIMMs.

- **Low Noise**

Low noise design (≤30 dB in idle status and ≤40 dB under full configuration), providing perfect user experience.

Specifications

Model	Maintenance	Cooling
K T3020-X2-A0-R0-00	Rear I/O	Air cooling
Processor	One Intel® Xeon® E-series Tatlow Platform or Pentium® series processor	
Memory	4 DDR5 DIMM slots, delivering a memory capacity of up to 128 GB Front: 4 × 3.5-inch SAS/SATA drives or	
Storage	4 × 2.5-inch SAS/SATA drives Internal: 1 × 2280/22110 SATA/PCIe M.2 SSD	
I/O Expansion Slot	Rear: 2 PCIe 4.0 expansion slots	
Power Supply	Single PSU with the output power of 300W/550W, or 1+1 redundant PSUs with the output power of 500W	
Operating Temperature	5°C to 35°C (For details, refer to the White Paper)	

KR2266V2

High-density 2U Storage Rack Server

Overview

The KR2266V2 is a high-density 2U2S storage-optimized server powered by the 4th Gen Intel® Xeon® Scalable processors. It features an innovative three-tier storage architecture that significantly improves storage density, computing power, network bandwidth, and intelligent management. In addition, the balanced and symmetric system architecture provides increased data capacity, larger data throughput, and stronger data processing capabilities, making it highly suitable for big data, CDN, hyper-converged storage, distributed storage, and other application scenarios.

KR2266V2 | Powered **Intel Processors**

Features

■ High-density Storage

Supports up to 38 drives in a 2U space, providing a 158% storage density increase compared to traditional 2U 12-drive servers. It also offers a maximum SSD:HDD ratio of 1:2 for high cache capacity, meeting the demands of large-capacity and high-density storage as well as high cache.

■ High Bandwidth

With I/O expansion capacities, the product supports PCIe 5.0 cards with a data rate of up to 32 GT/s, doubling the rate of PCIe 4.0 cards. It supports 400 Gb networking, enabling low-latency application experiences.

■ High Computing Power

Supports two 4th Gen Intel® Xeon® Scalable processors with up to 350W TDP and the computing performance 60% higher than that of its predecessor, meeting the increasing computing power demands of big data analysis services.

■ Intelligent Environmental Perception

With professional hardware and software design, the product can monitor the temperature, air flow, and air pressure of the operating environment in real time, intelligently control the cooling strategy to improve the drive life, and predict storage media faults through AI technology and give proper solutions to eliminate the faults, ensuring the stable operation of the system.

Specifications

Model	Maintenance	Cooling
KR2266-X2-A0-R0-00	Rear I/O	Air cooling

Processor	Up to two 4th Gen Intel® Xeon® Scalable processors
Memory	16 DDR5 DIMM slots, delivering a memory capacity of up to 8 TB
Storage	Front: Up to 24 × 3.5-/2.5-inch hot-swap SAS/SATA drives Internal: Up to 8 × 2.5-inch SAS/SATA drives Rear: Up to 8 × hot-swap 2.5-inch SAS/SATA/NVMe/E1.S drives or 4 × hot-swap 3.5-inch SAS/SATA drives | 2 × SATA/PCIe M.2 SSDs
I/O Expansion Slot	Up to 8 PCIe 5.0 slots, including 1 OCP 3.0 slot
Power Supply	1+1 redundant Platinum PSUs that support HVDC, and Titanium level PSUs
Operating Temperature	5°C to 40°C (For details, refer to the White Paper)

KR4266V2

General-purpose 4U Rack Storage Server

Overview

The KR4266V2 is a 4U2S general-purpose storage-optimized server powered by 4th Gen Intel® Xeon® Scalable processors. In a 4U space, it provides high storage capacity, powerful computing performance, ultimate I/O expansion capabilities and high energy efficiency, making itself highly suitable for application scenarios such as warm/cold data storage, video surveillance storage, big data storage and cloud storage pooling. In addition, the storage model adopts a multi-dimensional cooling solution incorporating both air cooling and cold-plated liquid cooling for the first time, satisfying the demand for low PUE in high-density data centers.

KR4266V2 | Powered **Intel Processors**

Features

■ High Storage Capacity

Supports up to 46 × 3.5-inch drives, providing an ultra-large storage capacity of up to 1 PB to meet local storage needs.

■ Ultimate I/O Expansion Capabilities

Up to 13 PCIe expansion slots that further improve I/O expansion capabilities and support multiple storage modules, network modules and GPU modules, enabling users to make flexible configurations for specific service needs, eliminate I/O bottlenecks and improve server performance.

■ High Energy Efficiency and Carbon Reduction

Supports cold-plated liquid cooling, providing comprehensive liquid cooling solutions for data centers to achieve a PUE below 1.1.

■ Powerful Computing Performance

The server features a complete series of new-generation processors, which can provide up to a 60% increase in computing performance compared to its predecessors. It also supports 2 dual-width GPUs or 8 single-width GPUs, meeting the needs of IVA scenarios and implementing efficient analysis of local data and real-time AI application.

Specifications

Model	Maintenance	Cooling
KR4266-X2-A0-R0-00	Rear I/O	Air cooling
KR4266-X2-C0-R0-00	Rear I/O	Cold-plated liquid cooling
Processor	Up to two 4th Gen Intel® Xeon® Scalable processors	
Memory	32 DDR5 DIMM slots, delivering a memory capacity of up to 16 TB	
Storage	Front: 24 × 3.5-inch hot-swap SATA/SAS drives Rear: 16 × 3.5-inch hot-swap SATA/SAS drives | 4 × 2.5-inch hot-swap SATA/SAS/NVMe SSDs | 2 × SATA/PCIe M.2 SSDs or 2 × E1.S SSDs | Up to 16 × U.2 NVMe SSDs Internal: 6 × 3.5-inch SATA/SAS drives | Up to 2 × TF cards	
I/O Expansion Slot	Up to 13 PCIe 5.0 slots, including 1 dedicated PCIe expansion slot for the RAID controller card and 2 OCP 3.0 slots	
Power Supply	1+1 redundant Platinum PSUs that support HVDC, and Titanium level PSUs	
Operating Temperature	5°C to 45°C (For details, refer to the White Paper)	

KR4276V2

High-density 4U Rack Storage Server

Overview

The KR4276V2 is a 4U2S high-capacity high-density storage rack server powered by 4th Gen Intel® Xeon® Scalable processors. With a compact size, flexible I/Os, energy saving and other ultimate designs, it provides a huge storage capacity to meet the user's current and future needs for service expansion. In a 4U space, the server supports 60 × 3.5-inch drives to meet the strict requirements on space and storage costs, making it suitable for cloud storage, video storage, big data, archiving and other application scenarios.

KR4276V2 | Powered **Intel Processors**

Features

■ Compact Size, Large Capacity

With innovative solutions, the server supports 60 × 3.5-inch drives in a 4U space, which maximizes the storage capacity and density and delivers a storage capacity of up to 1.3 PB.

■ Flexible I/O Design

The server provides both front and rear I/O configurations for you to choose from. The front I/O configuration innovates the design of the hot/cold aisle, reducing the average failure rate of thermo-sensitive components by over 90% and improving the service life of the components by over 300%.

■ Eco-friendly Energy Saving

The KAYTUS' power consumption management technology enables you to accurately monitor and control the power consumption of the system in real time. The KAYTUS' drive sleep mode technology enables you to customize the deep sleep of drives and elaborately manage and control the power consumption of the whole server, reducing the total power consumption by 70%.

Specifications

Model	Maintenance	Cooling
KR4276-X2-A0-R0-00	Rear I/O Front I/O Up to two 4th Gen Intel® Xeon® Scalable processors	Air cooling
KR4276-X2-A0-F0-00		Air cooling
Processor	32 DDR5 DIMM slots, delivering a memory capacity of up to 16 TB	
Memory	General	
Storage	Up to 60 × 3.5-inch hot-swap SAS/SATA drives 10 × 2.5-inch hot-swap SAS/SATA drives, up to 8 × NVMe drives (optional) 2 × SATA/PCIe M.2 SSDs	Front I/O Up to 60 × 3.5-inch hot-swap SAS/SATA drives Up to 4 × 2.5-inch SAS/SATA/NVMe SSDs 2 × SATA/PCIe M.2 SSDs
I/O Expansion Slot	Up to 9 PCIe 5.0 slots, including 2 OCP 3.0 slots	Up to 5 PCIe 5.0 slots, including 1 OCP 3.0 slot
Power Supply	1+1 redundant Platinum PSUs that support HVDC, and Titanium level PSUs	
Operating Temperature	5°C to 40°C (For details, refer to the White Paper)	

K24V2

2U4N High-density Multi-node Server for New-generation Data Centers

Overview

The K24V2 is a high-density multi-node server that features Intel & AMD platforms and offers 4 single- or dual-socket compute node options. It provides optimal performance, high reliability, intelligent PSU and fan control, and flexible storage configurations in a standard 2U cabinet, occupying less cabinet space and reducing energy consumption and cabinet deployment costs. The K24V2 is suitable for high-performance computing, virtualization and other computing-intensive application scenarios, providing flexible solutions for a variety of application scenarios with distributed system architectures, such as HPC, cloud resource pooling, and big data analysis.

K24V2-2S | Powered **Intel Processors**

Features

■ Intelligent O&M

The server supports node-level leak detection, with the liquid cooling cabinets integrated with dynamic loop monitoring equipment to intelligently monitor the temperature, humidity and leak information.

■ Leading Performance

Eight 4th Gen Intel® Xeon® Scalable processors in a 2U space,

with up to 350W TDP per CPU; 16 DDR5 DIMM slots per node; 400 Gb NDR Infiniband for high-bandwidth node interconnection.

■ Efficient Liquid Cooling

The cold plates carrying warm water cover CPUs, DIMMs and VR modules, with a liquid-cooling coverage ratio of over 80%, contributing to low PUE of only 1.1 and reducing the data center TCO by more than 30%.

■ Flexible Deployment

Exclusive mobile air- and liquid-cooling CDU solution supports integrated delivery of cabinets, simplifying the deployment procedure on customer's site.

Specifications

Chassis Model	Maintenance	Cooling
K24-X2-A0-R0-00	Rear I/O	Air cooling
K24-X2-C0-R0-00	Rear I/O	Cold-plated liquid cooling
Form Factor	2U rack chassis, including 4 independent hot-swap 2-socket compute nodes	
Storage	Configuration 1: 8 × 2.5-inch SSDs (7 mm) | Configuration 2: 4 × 2.5-inch SSDs (15 mm)	
Power Supply	4 N+N redundant hot-swap 2,200W Platinum/Titanium PSUs	
System Cooling	4 front 8086 system cooling fans with N+1 redundancy; liquid cooling enabled node	
Operating Temperature	5°C to 35°C	
Node Model	**Maintenance**	**Cooling**
KM1270-X2-A0-R0-00	Rear I/O	Air cooling
KM1270-X2-C0-R0-00	Rear I/O	Cold-plated liquid cooling
Form Factor	1U half-width 2-socket compute node	
Processor	Two 4th Gen Intel® Xeon® Scalable processors per node	
Memory	Up to 16 DDR5 DIMMs per node, delivering a memory capacity of up to 8 TB	
PCIe Expansion	Air cooling: 1 × PCIe 4.0 x16 slot + 1 × PCIe 5.0 x16 slot per node | Liquid cooling: 1 × PCIe 5.0 x16 slot per node	
I/O Expansion Slot	Front: 2 × USB 2.0 ports, 1 × VGA port, 1 × power button, and 1 × UID button per node | Rear: 1 × RJ45 port, 1 × UID button, 1 × RST button, 1 × micro USB for debug, and 1 × micro USB per node	
Storage	Configuration 1: 8 × 2.5-inch SSDs (7 mm) | Configuration 2: 4 × 2.5-inch SSDs (15 mm) | 2 × internal SATA/PCIe M.2 SSDs per node	

K24V2-1S | Powered by Intel Processors

Features

■ High Density, High Efficiency and Optimized System Architecture

Features the 4th Gen Intel® Xeon® Scalable processor, with up to 350W TDP; provides the highest virtual machine density, high core counts and ultimate performance in a single-CPU socket.
Four 2-socket server nodes can be deployed in a 2U space, which quadruples the computing density of a 2U rack server and thus greatly improves the space usage efficiency of customers' server rooms

■ High Cost Performance

Flexible adaptability to PCIe 4.0/PCIe 5.0 rate, providing cost-effective options.
Power capping helps achieve system-level efficiency and energy saving.
The use of extended volume air cooling (EVAC) heatsinks significantly optimizes the fan speed and reduces the system power.

■ Extreme Performance and Flexible Adaptability

U p to 24 × 2.5-inch NVMe/SAS/SATA drives, 8 × E1.S SSDs, or configuration with no drives or backplanes.
Up to 2 optional internal SATA/NVMe M.2 SSDs modules, meeting diverse storage needs.

Specifications

Chassis Model	Maintenance	Cooling
K24-X2-A0-R0-00	Rear I/O	Air cooling
Form Factor	2U rack chassis, including 4 independent hot-swap single-socket compute nodes	
Storage	24 × 2.5-inch SSDs (7 mm)/8 × E1.S SSDs	
Power Supply	4 hot-swap 2,200W/2,000W Platinum/Titanium PSUs with N+N redundancy	
System Cooling	6 front 6056 system cooling fans with N+1 rotor redundancy	
Operating Temperature	5°C to 35°C	
Node Model	**Maintenance**	**Cooling**
KM1160-X2-A0-R0-00	Rear I/O	Air cooling
Form Factor	1U half-width single-socket computing node	
Processor	One 4th Gen Intel® Xeon® Scalable processor per node	
Memory	Up to 8 DDR5 DIMMs per node, delivering a memory capacity of up to 4 TB	
PCIe Expansion	2 × PCIe 5.0 x16 slots per node	
I/O Expansion Slot	Front: 2 × USB 2.0 ports, 1 × VGA port, 1 × power button, and 1 × UID button per node Rear: 1 × RJ45 port, 1 × UID button, 1 × RST button, 1 × micro USB for debug, and 1 × micro USB per node Internal: 1 × USB 3.0 port per node	
Storage	24 × front 2.5-inch SSDs or 8 × front E1.S SSDs, and 2 × internal SATA/PCIe M.2 SSDs per node	

K24V2-2S | Powered by AMD Processors

Features

■ Intelligent O&M

The server supports node-level leak detection, with the liquid cooling cabinets integrated with dynamic loop monitoring equipment to intelligently monitor the temperature, humidity and leak information.

■ Leading Performance

Eight 4th Gen AMD EPYCTM processors in a 2U space
24 DDR5 DIMM slots per node, delivering a memory capacity of up to 12 TB
400 Gb NDR Infiniband for high-bandwidth node interconnection.

■ Efficient Liquid Cooling

The cold plates carrying warm water cover CPUs, DIMMs and VR modules, with a liquid-cooling coverage ratio of over 80%, contributing to low PUE of only 1.1 and reducing the data center TCO by more than 30%.

■ Flexible Deployment

Exclusive mobile air- and liquid-cooling CDU solution supports integrated delivery of cabinets, simplifying the deployment procedure on customer's site.

Specifications

Chassis Model	**Maintenance**	**Cooling**
K24-E2-A0-R0-00	Rear I/O	Air cooling
K24-E2-C0-R0-00	Rear I/O	Cold-plated liquid cooling
Form Factor	2U rack chassis, including 4 independent hot-swap 2-socket compute nodes	
Storage	8 × 2.5-inch SSDs (7 mm)	
Power Supply	4 N+N redundant hot-swap 2,200W Platinum/Titanium PSUs	
System Cooling	4 front 8086 system cooling fans with N+1 redundancy; liquid cooling enabled node	
Operating Temperature	5°C to 35°C	
Node Model	**Maintenance**	**Cooling**
KM1280-E2-A0-R0-00	Rear I/O	Air cooling
KM1280-E2-A0-R0-00	Rear I/O	Cold-plated liquid cooling
Form Factor	1U half-width 2-socket compute node	
Processor	Two 4th Gen AMD EPYCTM processors per node	
Memory	Up to 24 DDR5 DIMMs per node, delivering a memory capacity of up to 12 TB	
PCIe Expansion	Air cooling: 1 × PCIe 4.0 x16 slot + 1 × PCIe 5.0 x16 slot per node | Liquid cooling: 1 × PCIe 5.0 x16 slot per node	
I/O Expansion Slot	Front: 2 × USB 2.0 ports, 1 × VGA port, 1 × power button, and 1 × UID button per node Rear: 1 × RJ45 port, 1 × UID button, 1 × RST button, 1 × micro USB for debug, and 1 × micro USB per node Internal: 1 × USB 3.0 port per node	
Storage	8 front 2.5-inch SSDs (7 mm) and 2 internal SATA/PCIe M.2 SSDs per node	

K24V2-1S

Powered by
Intel Processors

AMD EPYC

Features

■ **High Density, High Efficiency and Optimized System Architecture**

Features the 4th Gen AMD EPYCTM processor, with up to 96 cores, 196 threads, up to 400W TDP, a boost frequency of 4.4 GHz, and an L3 cache of up to 384 MB per CPU; provides the highest virtual machine density, high core counts and ultimate performance in a single-CPU socket.
Four 2-socket server nodes can be deployed in a 2U space, which quadruples the computing density of a 2U rack server and thus greatly improves the space usage efficiency of customers' server rooms.

■ **High Cost Performance**

Flexible adaptability to mother- board/ riser cards supporting PCIe4.0/5.0, providing cost-effective options.
Power capping helps achieve system-level efficiency and energy saving.
The use of extended volume air cooling (EVAC) heatsinks significantly optimizes the fan speed and reduces the system power.

■ **Extreme Performance and Flexible Adaptability**

U p to 24 × 2.5-inch NVMe/SAS/SATA-drives or 8 × E1.S SSDs, or configuration with no drives or backplanes.
Up to 2 optional internal SATA/NVMe M.2 SSD modules, meeting diverse storage needs.

Specifications

Chassis Model	**Maintenance**	**Cooling**
K24-E2-A0-R0-00	Rear I/O	Air cooling
Form Factor	2U rack chassis, including 4 independent hot-swap single-socket compute nodes	
Storage	24 × 2.5-inch SSDs (7 mm)/8 × E1.S SSDs	
Power Supply	4 hot-swap 2,200W/2,000 W Platinum/Titanium PSUs with N+N redundancy	
System Cooling	6 front 6056 system cooling fans with N+1 rotor redundancy	
Operating Temperature	5°C to 35°C	
Node Model	**Maintenance**	**Cooling**
KM1160-E2-A0-R0-00	Rear I/O	Air cooling
Form Factor	1U half-width single-socket computing node	
Processor	One 4th Gen AMD EPYCTM processor per node	
Memory	Up to 12 DDR5 DIMMs per node, delivering a memory capacity of up to 6 TB	
PCIe Expansion	2 × PCIe 5.0 x16 slots per node	
I/O Expansion Slot	Front: 2 × USB 2.0 ports, 1 × VGA port, 1 × power button, and 1 × UID button per node Rear: 1 × RJ45 port, 1 × UID button, 1 × RST button, 1 × micro USB for debug, and 1 × micro USB per node Internal: 1 × USB 3.0 port per node	
Storage	24 × front 2.5-inch SSDs or 8 × E1.S SSDs, and 2 × internal SATA/PCIe M.2 SSDs per node	

KR2460V2

Cloud Optimization-oriented 2U 4-socket Rack Server for High-density Computing Platforms

Overview

The KR2460V2 is a high-end 4-socket rack server that features the 4th Gen Intel® Xeon® Scalable processors. It meets the demands for high computing performance and large memory capacity, and also provides good solutions for customers having density and storage requirements. Hence, it is perfect for application scenarios requiring high-density servers, such as virtualization, database, SAP HANA, and HPC.

KR2460V2 | Powered **Intel Processors**

Features

▪ High-density Computing Performance

processors integrated in a 2U space, with up to 60 cores, 120 threads, and up to 350W TDP per CPU; 3 UPI links per CPU at up to 16 GT/s; 64 DDR5 ECC DIMMs (RDIMMs) at 4,800 MT/s, delivering superior speed, high availability, and a memory capacity of up to 32TB.

▪ Diverse Storage Configurations

Up to 24 × front 2.5-inch SAS/SATA/NVMe/E3.S drives or 25 × front 2.5-inch SAS/SATA drives, and 2 × internal M.2 SSDs, meeting diverse storage needs.

▪ Extremely High Scalability

Up to 9 rear PCIe expansion slots and 2 OCP 3.0 slots that can flexibly configure 1/10/25/100 Gb NICs, providing multiple network interfaces options and a more flexible network structure for applications.

Specifications

Model	Maintenance	Cooling
KR2460-X2-A0-R0-00	Rear I/O	Air cooling Air cooling
KR2460-X2-A0-F0-00	Front I/O	Cold-plated liquid cooling
KR2460-X2-C0-R0-00	Rear I/O	
Processor	Two or four 4th Gen Intel® Xeon® Scalable processors	
Memory	64 DDR5 DIMM slots, delivering a memory capacity of up to 32 TB	
Storage	**General** Front: 24 × 2.5-inch SAS/SATA/NVMe/E3.S drives | 24 × E3.S SSDs | 25 × 2.5-inch SAS/SATA drives Internal: 2 × M.2 SSDs	**Front I/O** Front: 8 × 2.5-inch SAS/SATA/NVMe drives
I/O Expansion Slot	Up to 9 PCIe expansion slots and 2 OCP 3.0 slots	Up to 6 front PCIe expansion slots
Power Supply	1+1 redundant PSUs with the output power of 800W/1,300W/1,600W/2,000W/3,200W	
Operating Temperature	5°C to 45°C (For details, refer to the White Paper)	

KR4480V2

4U 4-socket Mission Critical Server for Highly-scalable Computing Platforms

Overview

The KR4480V2 is a high-end 4-socket rack server that features the 4th Gen Intel® Xeon® Scalable processors. Optimized with powerful computing performance, flexible modular design, excellent scalability, better reliability and security features for customers' data-intensive critical services, it is suitable for application scenarios such as large transaction databases, in-memory databases, virtualization integration, HPC, deep learning, and ERP.

KR4480V2 | Powered Intel Processors

Features

■ Powerful Computing Performance

Two or four 4th Gen Intel® Xeon® Scalable processors, with up to 60 cores, 120 threads, and up to 350W TDP per CPU; 3 UPI links per CPU at up to 16 GT/s; 64 DDR5 ECC DIMMs (RDIMMs) at 4,800 MT/s, delivering superior speed, high availability, and a memory capacity of up to 32 TB.

■ Diverse Storage Configurations

Up to 24 × front 2.5-inch SAS/SATA/NVMe drives or 25 × front 2.5-inch SAS/SATA drives, and 2 × internal M.2 SSDs, meeting diverse storage needs.

■ Extremely High Scalability

The server supports up to 16 PCIe expansion slots, including 1 dedicated slot for the OCP 3.0 card, or up to 15 PCIe expansion slots, including 2 dedicated slots for OCP 3.0 cards, providing multiple network port options and a more flexible network structure for applications.

Specifications

Model	Maintenance	Cooling
KR4480-X2-A0-R0-00	Rear I/O	Air cooling

Processor	Two or four 4th Gen Intel® Xeon® Scalable processors
M emory	64 DDR5 DIMM slots, delivering a memory capacity of up to 32 TB
Storage	Front: 24 × 2.5-inch SAS/SATA/NVMe drives, 25 × 2.5-inch SAS/SATA drives, 21 × 2.5-inch SAS/SATA drives + 4 × 2.5-inch SAS/SATA/NVMe drives, or 12 × 3.5-inch SAS/SATA drives + 8 × 2.5-inch SAS/SATA/NVMe drives Internal: 8 × SATA drives; NVMe RAID key; 2 × 2280/22110 M.2 SSDs with software and hardware RAID supported; 2 × TF cards Up to 16
I/O Expansion Slot	PCIe expansion slots, including 1 dedicated slot for the OCP 3.0 card; or up to 15 PCIe expansion slots, including 2 dedicated slots for OCP 3.0 cards
Power Supply	1+1 redundant PSUs with the output power of 800W/1,300W/1,600W/2,000W
Operating Temperature	5°C to 45°C (For details, refer to the White Paper)

KR6880V2

High-end 8-socket Rack Server

Overview

The KR6880V2 is a high-end 8-socket server powered by 4th Gen Intel® Xeon® Scalable processors. With superb computing- performance and extremely high reliability, it is dedicated for customers' mission critical applications and is perfect for scenarios such as large-scale transaction databases, SAP HANA, ERP, HPC, and mission critical virtualization.

KR6880V2 | Powered Intel Processors

Features

■ Superb Computing Performance

Eight 4th Gen Intel® Xeon® Scalable processors, UPI links at up to 16 GT/s, fully upgraded DDR5 and PCIe 5.0, and I/O-balanced design that significantly reduces I/O access latency and improves entire server performance.

■ Ultra-high Stability Design

The server adopts a fully modular design, with full redundancy of critical vulnerable components and chips; it includes SmartPPR supported memory and PSUs that supports dynamic power capping; it also supports the fault warning mechanism that prioritizes prevention over troubleshooting.

■ Easy Maintenance

The server supports dynamic load monitoring and intuitive display of its load status; supports LCD display to improve human-machine interaction experience; supports embedded oscilloscope and memory offline diagnosis to quickly locate faults. It also supports one-click BIOS setting mode to perfectly match customers' service applications.

Specifications

Model	Maintenance	Cooling
KR6880-X2-A0-R0-00	Rear I/O	Air cooling
Processor	Eight 4th Gen Intel® Xeon® Scalable processors	
Memory	128 DDR5 DIMM slots, delivering a memory capacity of up to 64 TB	
Storage	Front: Up to 24 × 2.5-inch SAS/SATA/NVMe drives Internal: 2 M.2 SSDs with software and hardware RAID supported, and up to 3 TF cards	
I/O Expansion Slot	Up to 18 PCIe slots, including 2 dedicated slots for RAID controller cards, and up to 4 OCP 3.0 slots	
Power Supply	4 standard N+M redundant CRPS PSUs with the output power of 1,300W/1,600W/2,000W/2,200W/2,700W	
Operating Temperature	5°C to 45°C (For details, refer to the White Paper)	

Ultimate Innovation

Rigorous Standards Guarantee High Product Quality

KAYTUS has dedicated labs for product quality testing and process development. Thousands of tests in 40 categories are provided for the entire lifecycle of servers from development to components, production, delivery and O&M. The labs conduct more than 2,000 tests on each product, including over 30 extreme-use tests.

Mechanical Environment Test

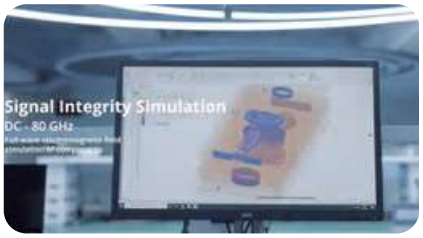
Each product is subjected to thousands of shocks and drops. In particular, the test to simulate a magnitude 9 earthquake goes beyond the existing standard for earthquake resistance (magnitude 8) for most buildings.

Climatic Environment Test

The eight test categories, including highly accelerated life tests (HALT), high temperature, low temperature, high humidity, low humidity, temperature and humidity cycling, rapid temperature cycling and thermal shock, ensure that products can withstand harsh climates.

Power Integrity (PI) Test

The industry's first automated PI test platform covering the entire process allows dynamic response testing at 40% higher stress than standard testing.



Signal Integrity (SI) Simulation

Full-wave electromagnetic field simulation at DC 80 GHz analyzes signal transmission, reflection, and matching properties of 3D structures of server components.

Signal Integrity Test

The industry's first fully automated press-contact SI testing platform has positioned accuracy down to the μm range, delivering a tenfold increase in efficiency.

Electromagnetic Compatibility Test

This test simulates the interference of static electricity, lightning strikes, voltage transients, electrical fast transient bursts, power-frequency magnetic fields, and radiation emission in complex electromagnetic environments.

Structural Heat Dissipation Test

Accurate wind tunnel measurements ensure that fan and air duct designs meet fluid mechanics requirements and maximize heat dissipation performance to reduce power consumption by 8%.

Failure Analysis Test

46 tests in 6 categories include the PCB and component failure analysis; analysis of physical, chemical, and mechanical properties, and board reliability test.

DC Business Simulation Test

The world's largest aging stress test line supports concurrent stress testing on 6400 servers for up to 50 hours.

Digiclean

Contact Us

Johannesburg Office
22 Mac-Mac Road Waterfall Office Park, Vorna Valley, Midrand, 1685

Cape Town Office
2 Enterprise Park, Enterprise Way, Sandown, Cape Town, 7441

Telephone
+27(0)10 312 6424

Email
sales@digiclean.co.za

Website
www.digiclean.co.za